

*Adm
BIS*

5. (ONCE AMENDED) An assembly as claimed in claim 4, wherein said resin layer is so patterned as to be absent around wiring portions protruding from said electronic devices, around passive devices mounted between said electronic devices, around portions of circuit surfaces of said electronic devices where resin forming said resin layer effects a device characteristic, around electrode pads, and around bumps formed on said electrode pads.

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7. (ONCE AMENDED) An assembly as claimed in claim 6, wherein said resin layer is so patterned as to be absent around wiring portions protruding from said electronic devices, around passive devices mounted between said electronic devices, around portions of circuit surfaces of said electronic devices where resin forming said resin layer effects a device characteristic, around electrode pads, and around bumps formed on said electrode pads.

8. (ONCE AMENDED) An assembly as claimed in claim 1, wherein said resin layer is so patterned as to be absent around wiring portions protruding from said electronic devices, around passive devices mounted between said electronic devices, around portions of circuit surfaces of said electronic devices where resin forming said resin layer effects a device characteristic, around electrode pads, and around bumps formed on said electrode pads.